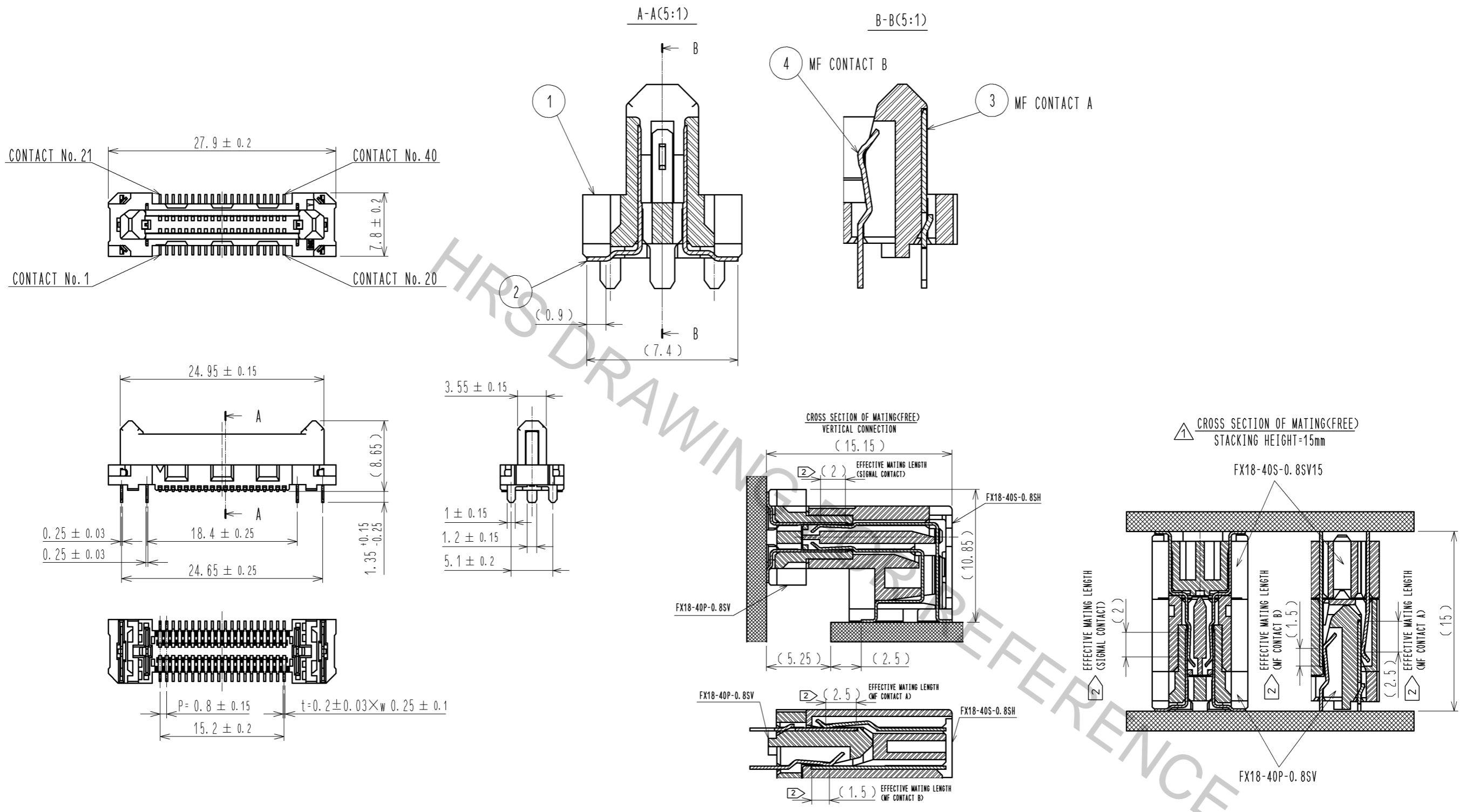


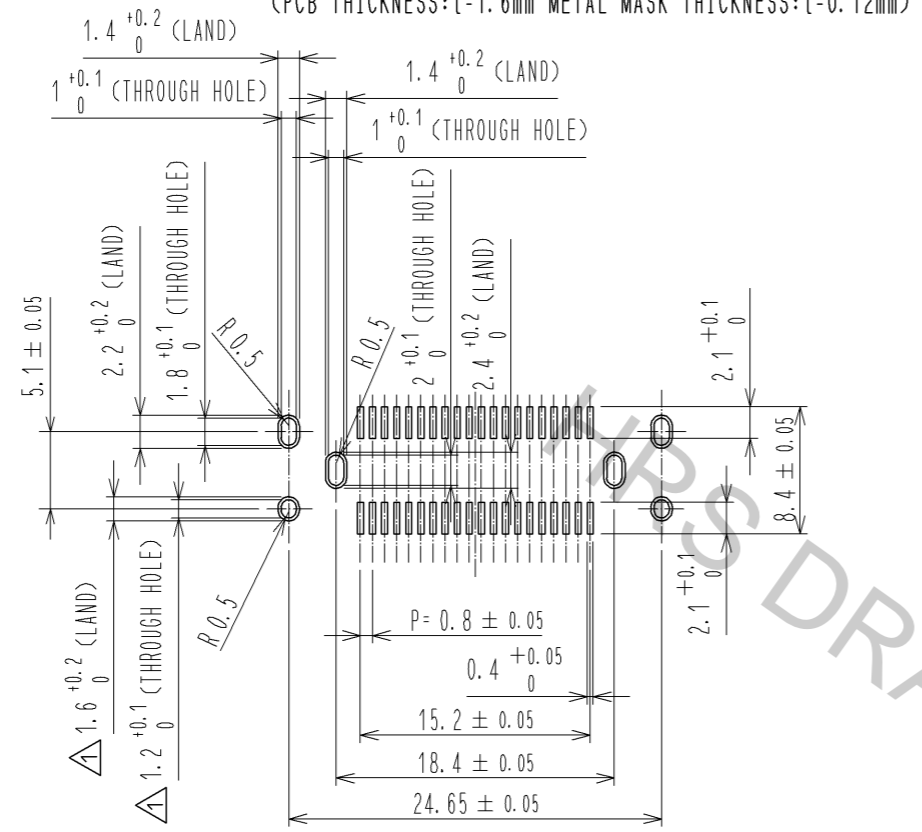
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- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.  
 ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)  
 WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.  
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)  
 ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)  
 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.  
 ⑤ THIS IS PACKAGED IN TRAY. (70pcs/TRAY)  
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.  
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

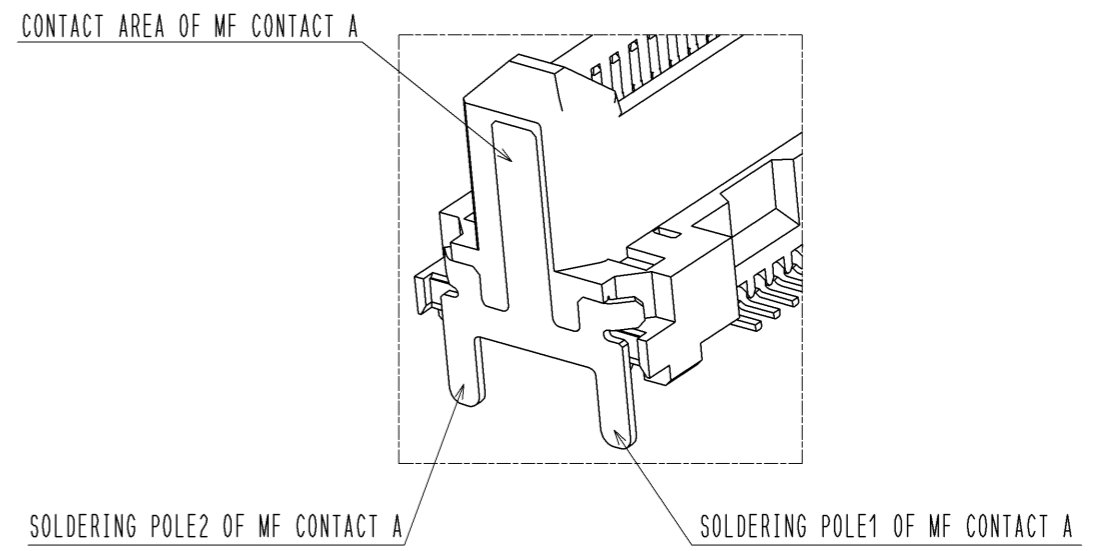
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	6	POLYIMIDE				
		LEAD AREA:TIN-PLATING 1 μm						
2	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3 μm	5	POLYSTYRENE				
		CONTACT AREA:GOLD 0.1 μm						
1	POLYAMIDE	LEAD AREA:GOLD 0.03 μm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm			
		UNDER PLATING:NICKEL 1.3 μm			LEAD AREA:TIN-PLATING 1 μm			
		BLACK UL94V-0			UNDER PLATING:NICKEL 1.3 μm			
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS	
UNITS mm		SCALE 2 : 1	COUNT 4	DESCRIPTION OF REVISIONS DIS-F-005578		DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 11.07.21
<b>HRS</b> HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	09.10.09	DRAWING NO. EDC3-159560-00				
		CHECED : KI. HIROKAWA	09.10.09	PART NO. FX18-40P-0.8SV				
		DESIGNED : TH. SANO	09.10.09	CODE NO. CL579-0016-0-00				
		DRAWN : TH. SANO	09.10.09					

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

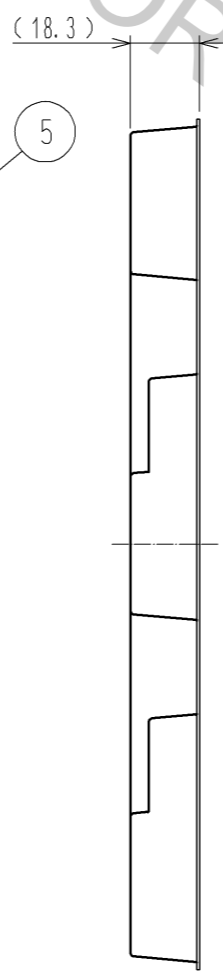
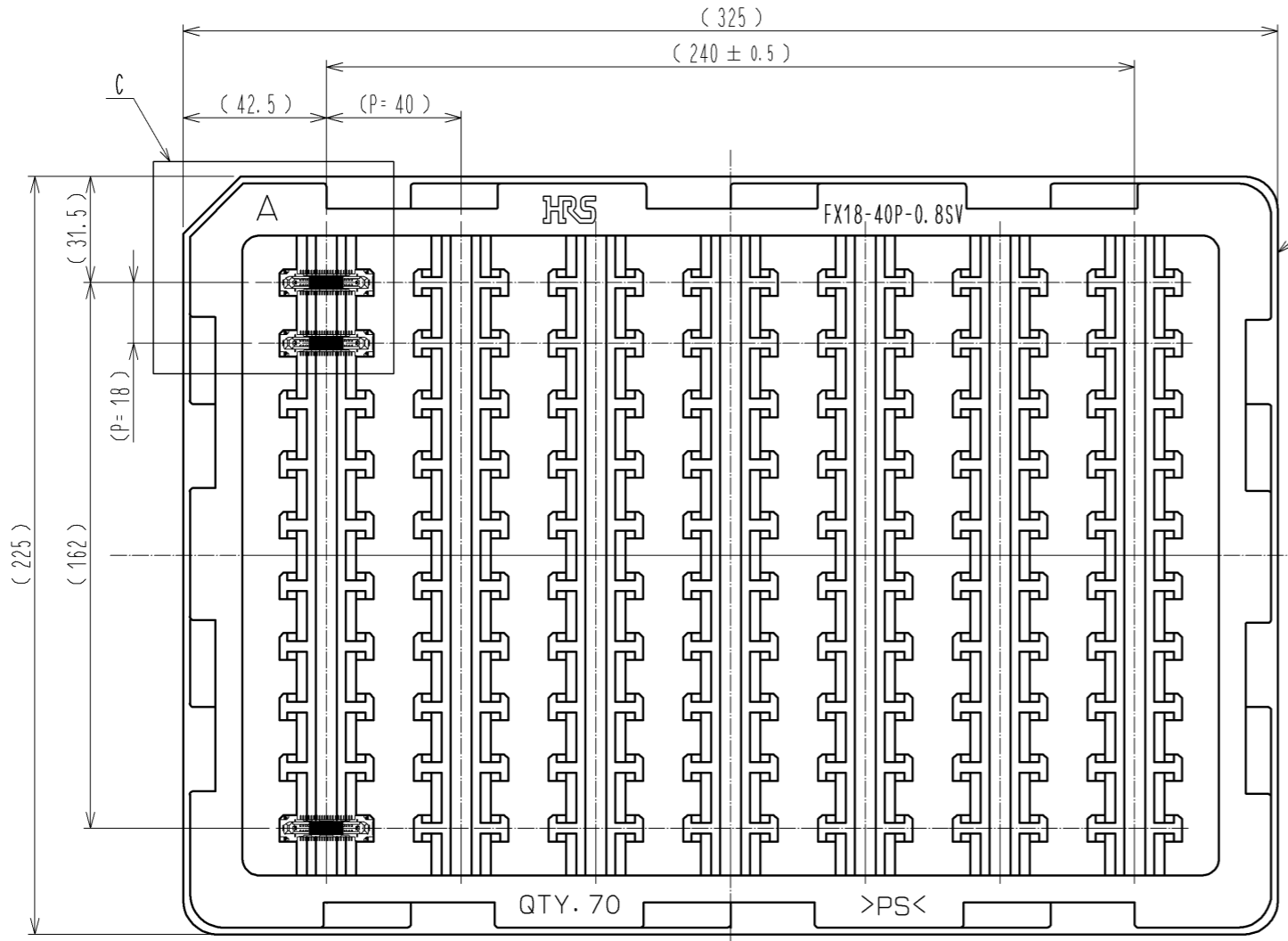


5 DRAWING FOR PACKING(1:2)

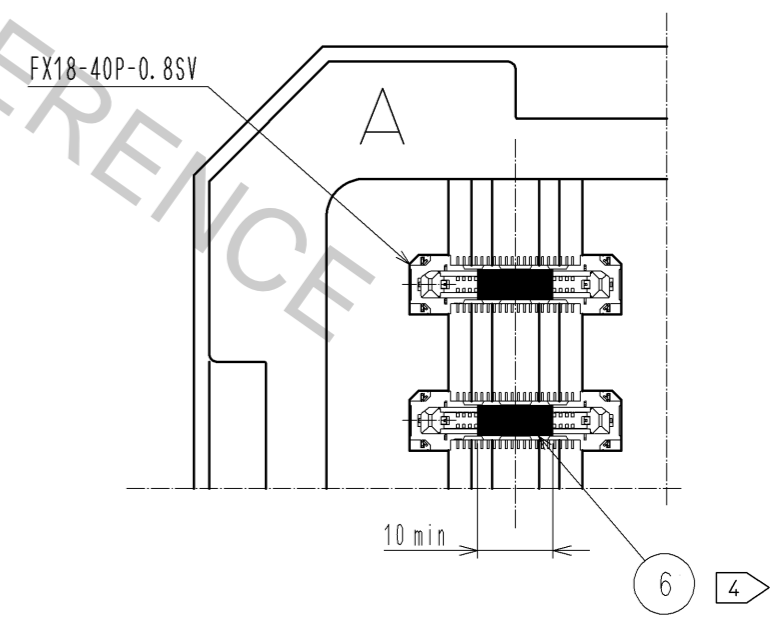
8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



C(1:1)



<b>HRS</b>	DRAWING NO.	EDC3-159560-00	2/2
	PART NO.	FX18-40P-0.8SV	
	CODE NO.	CL579-0016-0-00	